



- ASSEMBLY at uniboard PCB 2773 B/C:
- 1) Q1, D2 OPEN
  - 2) L2, L3 OPEN / L4 SHORT
  - 3) C6, C12, C13, C14, C15, C27, C28 OPEN
  - 4) R4, R13 OPEN / R6, R14 SHORT
  - 5) ref des >100 mounted externally
  - 6) R11 will not meet pattern

- NOTES:
- 1) R9 for test purposes only
  - 2) R101, R102 optional for ZERO load condition
  - 3) for lower ripple at +Vout add C12 22uF

Revision History	
Revision	Notes
A	* First release

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Number: PMP10091 Rev: A  
 SVN Rev: Not in version control  
 Drawn By:  
 Engineer: B.Geck

Designed for: Public Release Mod. Date: 8/22/2014  
 Project Title: 9W Dual Boost  
 Sheet Title:  
 Assembly Variant: Variant name not interpreted Sheet: 1 of 1  
 File: PMP10091RevA.SchDoc Size: A4  
 Contact: <http://www.ti.com/support>



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